



EM Noise Mitigation in Circuit Boards and Cavities

*Omar M. Ramahi, Xin Wu, Lin Li, Baharak Mohajeriravani, Shahrooz Shahparnia,
Neil Goldsman, and Xi Shao
Mechanical Engineering Department,
Electrical and Computer Engineering Department and
CALCE Electronic Products and Systems Center
University of Maryland, College Park, MD*

Microwave Effects and Chaos in 21st Century Analog & Digital Electronics
AFOSR MURI
November 2003 Review
MURI contract F496200110374
Chicago, IL
November 14-15, 2003



Previous Work and Recent Work

- Developing 3-dimensional full-wave predictive tools for cavity Resonance and S Parameters

[completed]

- Developing fast predictive modeling tools for PCB analysis

[completed]

- Using lossy material coating to reduce aperture radiation

[parametric study; experimental validation]



Previous Work and Recent Work

❑ Reducing noise in printed circuit boards using high impedance surface

[experimental verification; concept improvement; wideband extension]

❑ Reduction of coupling between cavities using high-impedance surfaces

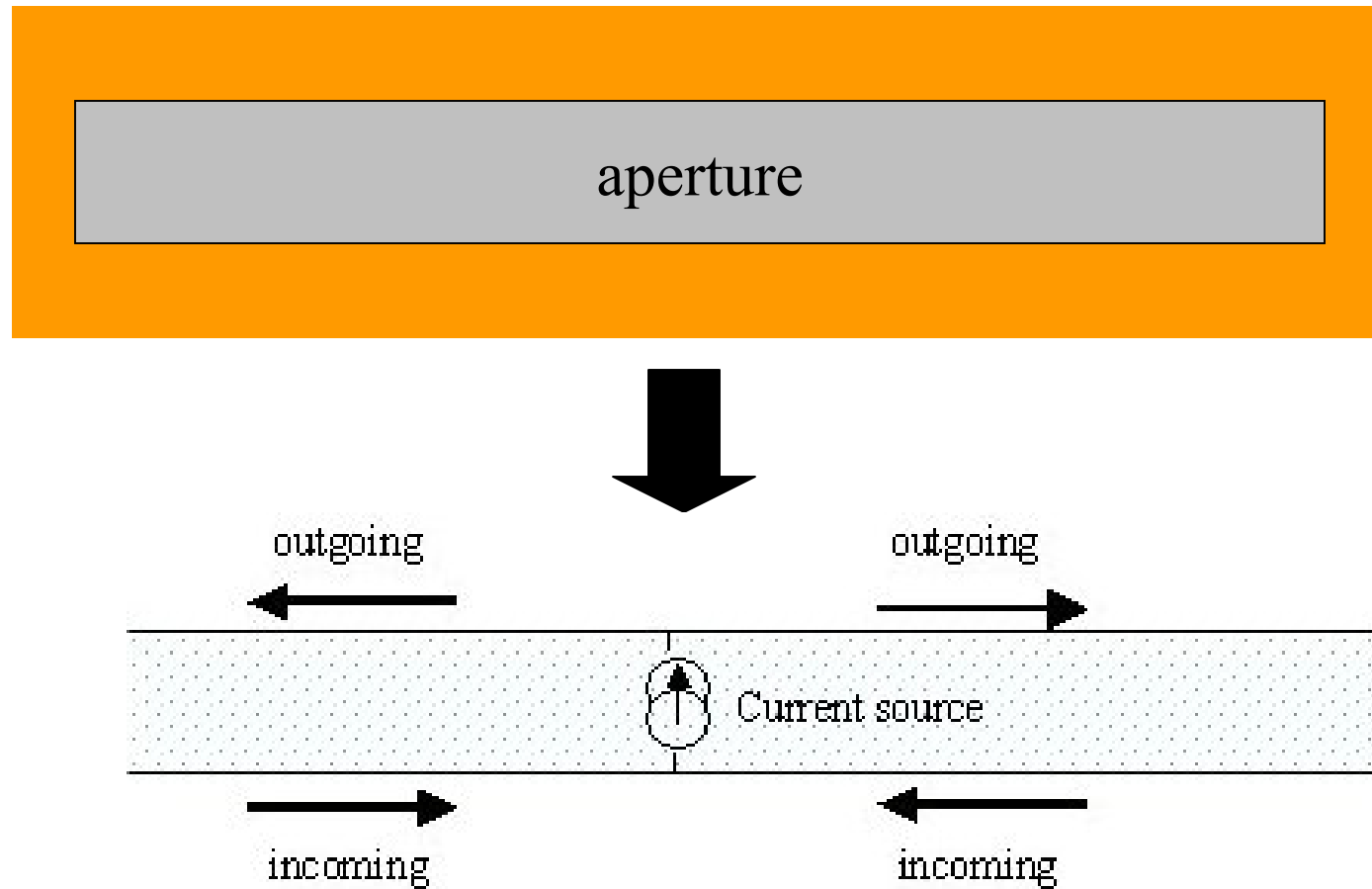
[concept validation through numerical experiments]



Part I:
Noise mitigation from apertures
without reduction of
aperture size

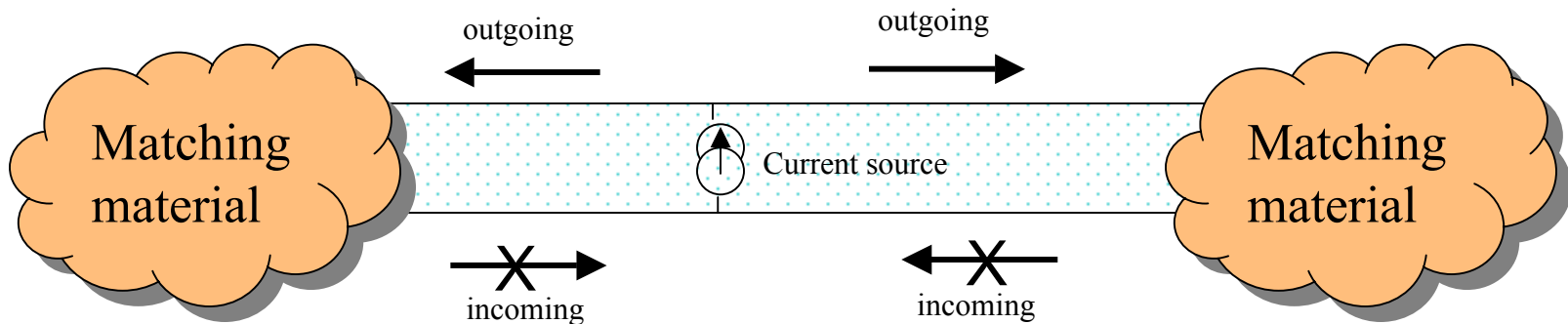
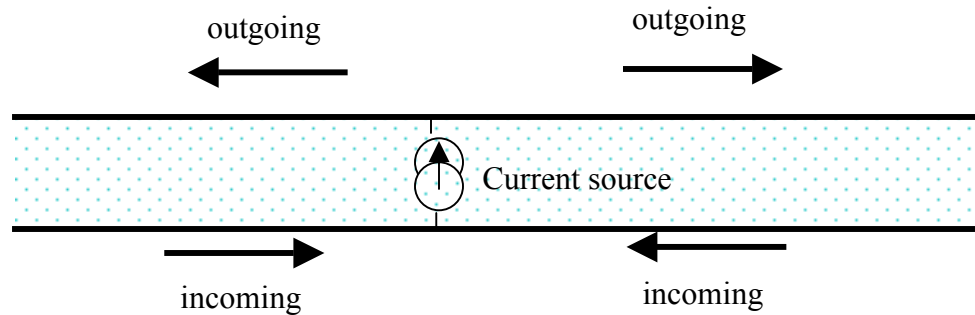


Transmission Line Interpretation of Apertures



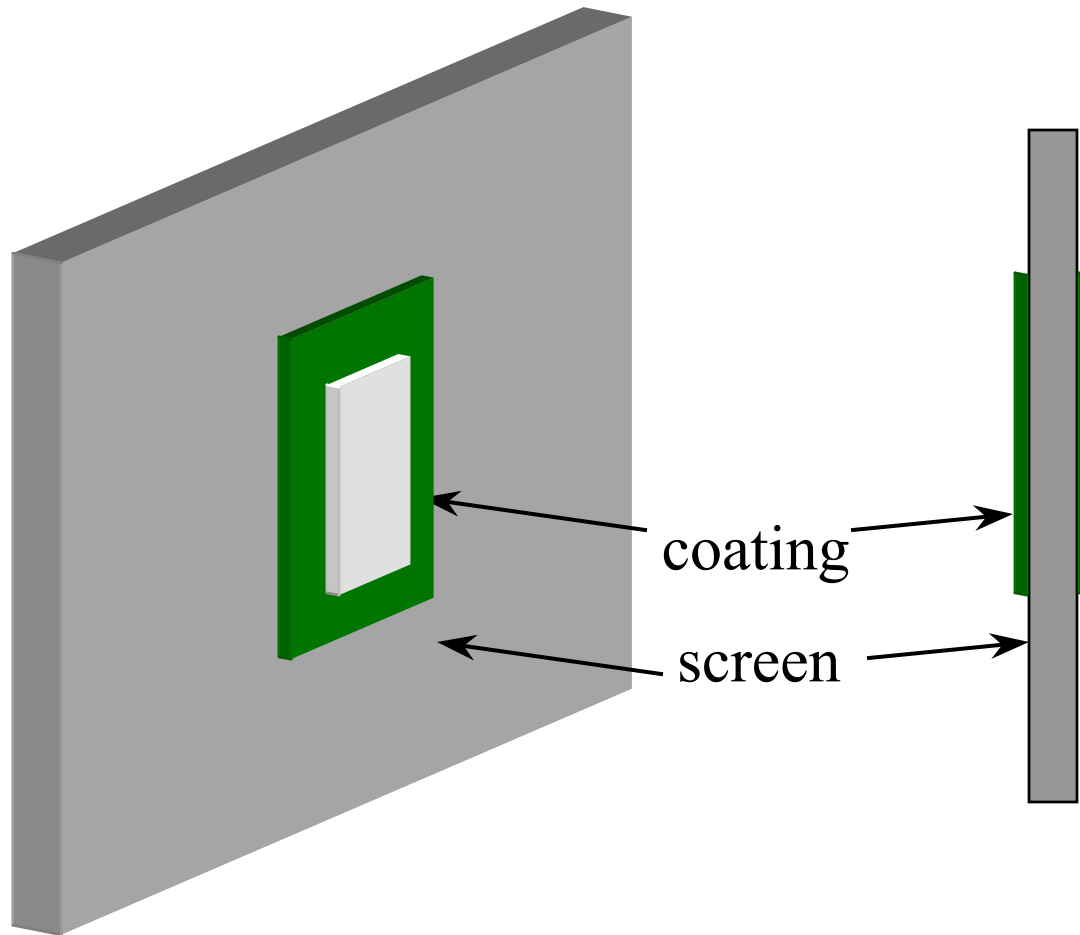


Transmission Line Interpretation of Apertures with Matched Termination



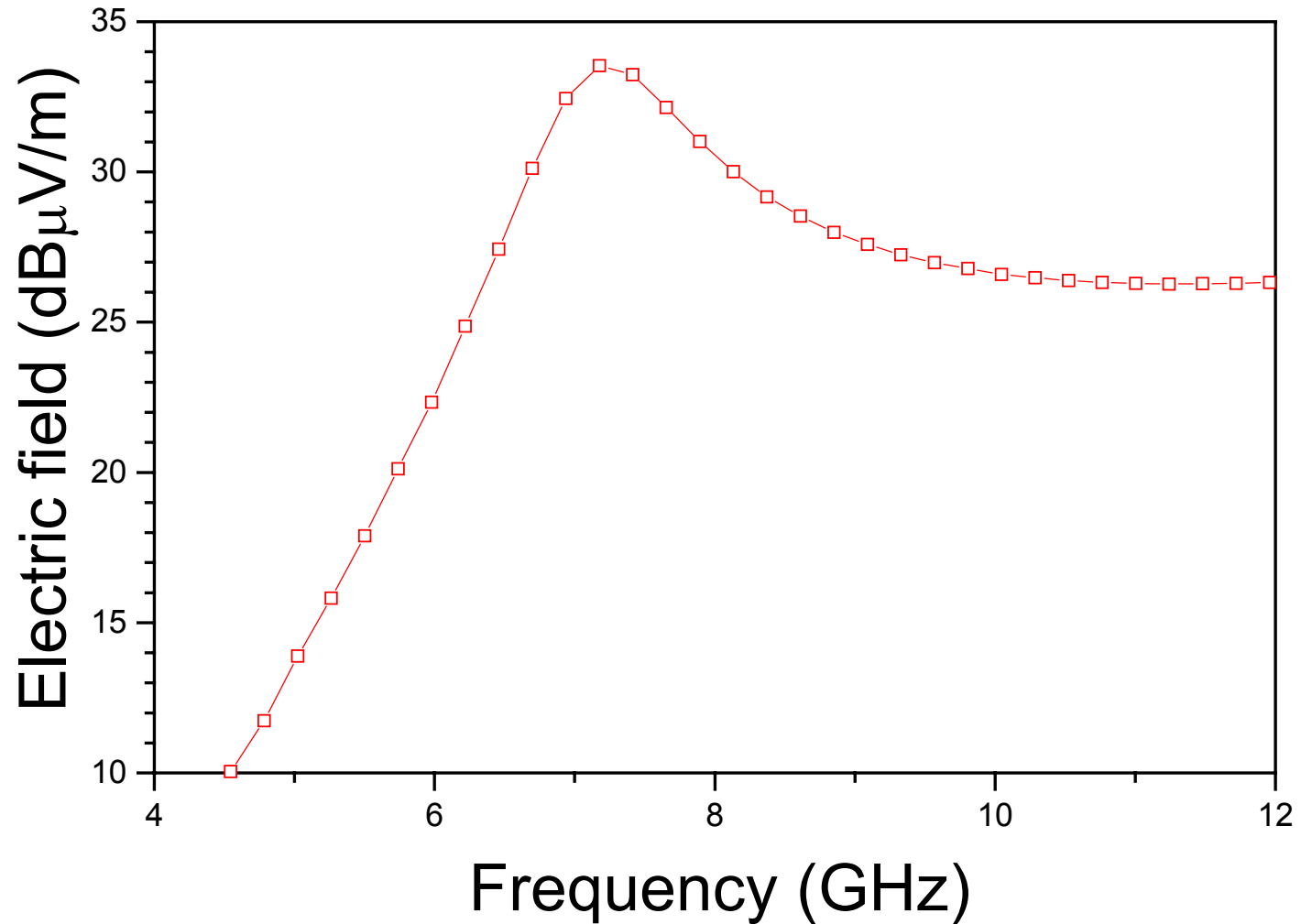


“Loaded” Aperture



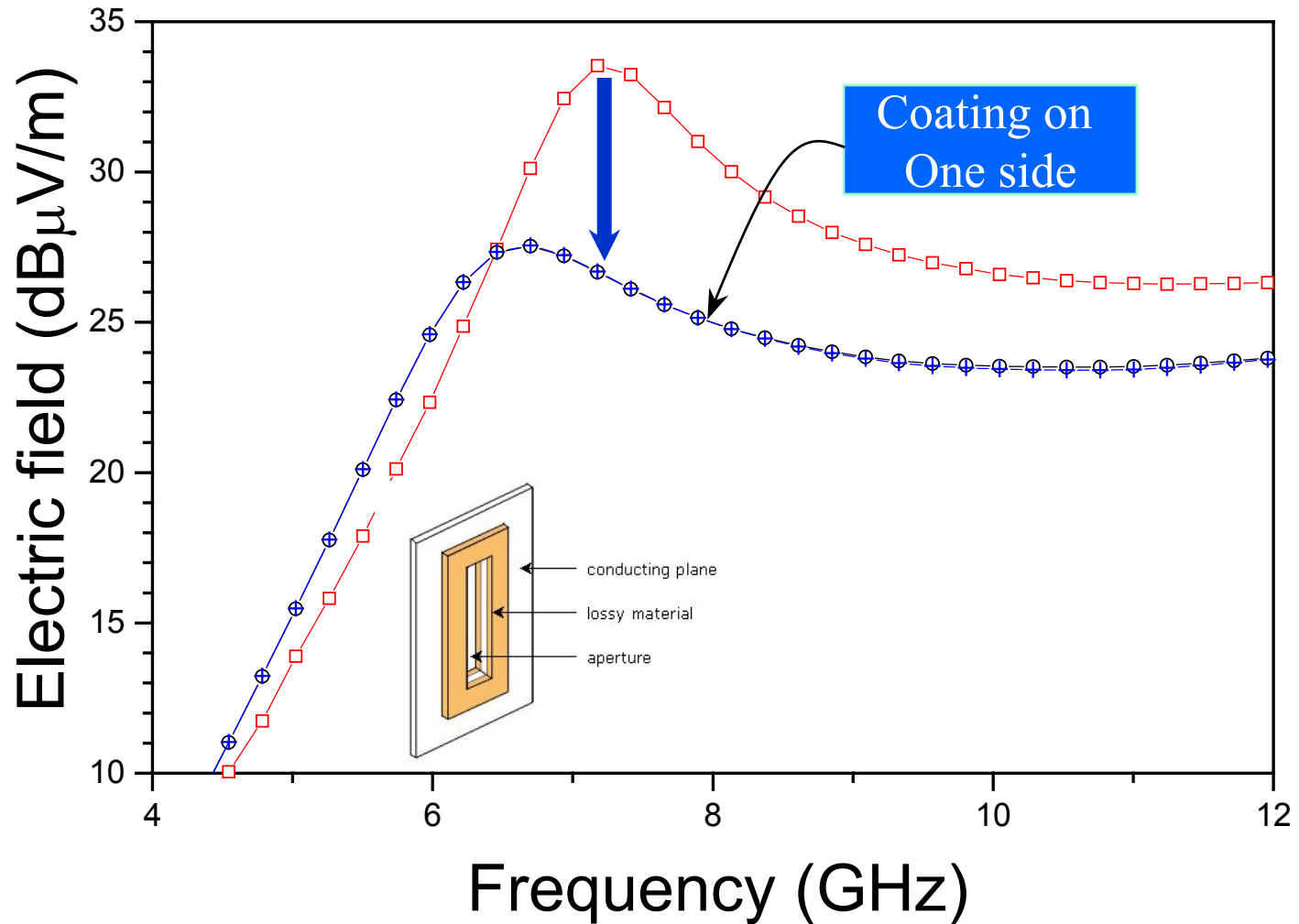


Aperture without Coating



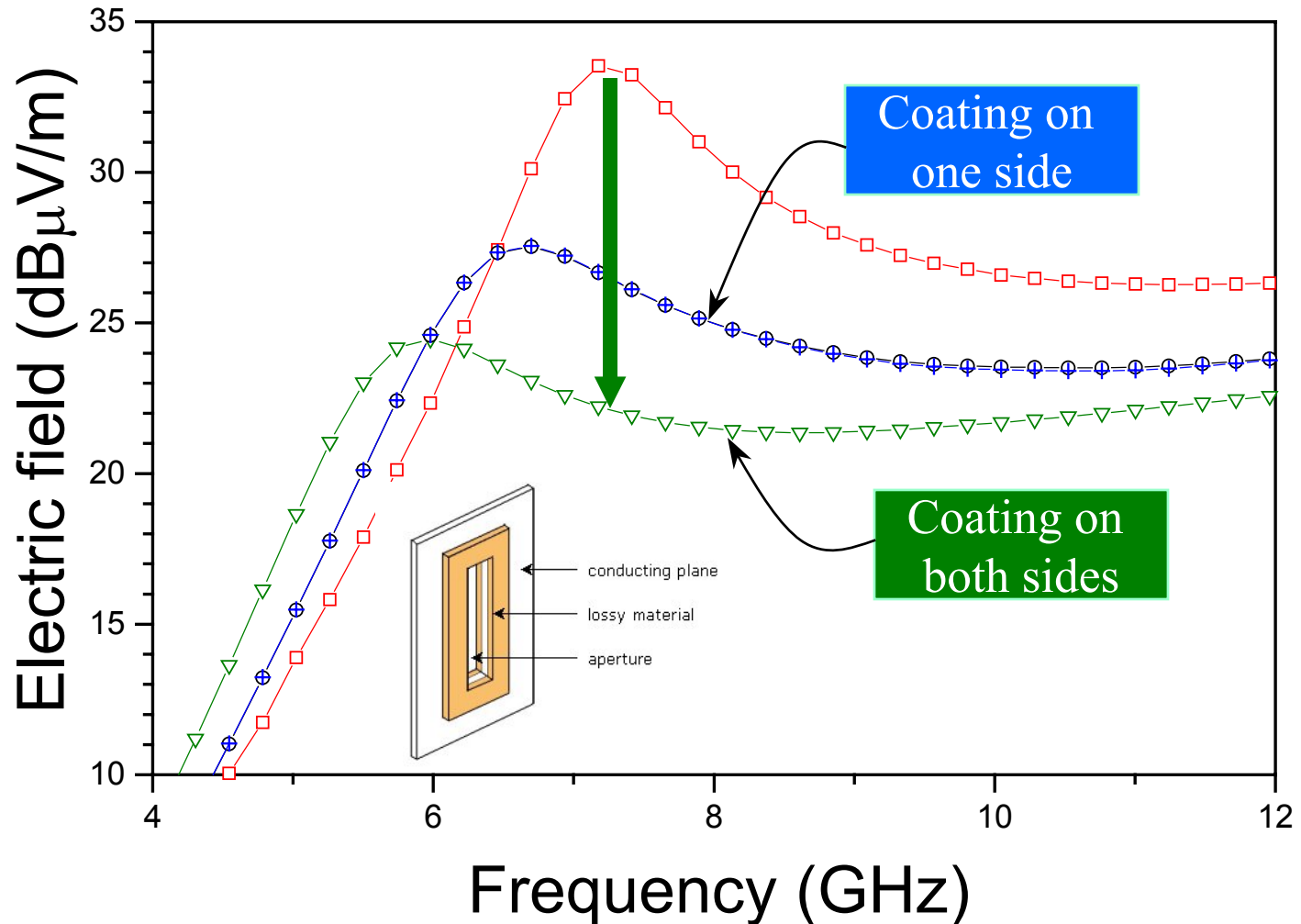


Reduction of Radiated Field at Resonance



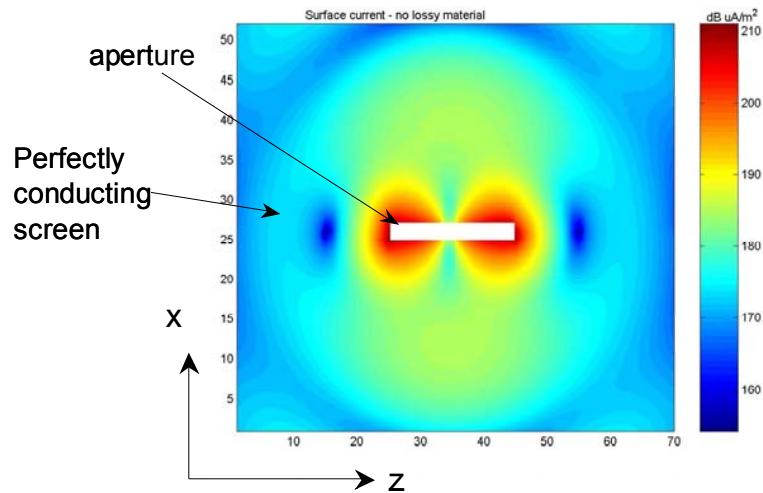


Reduction of Radiated Field at Resonance

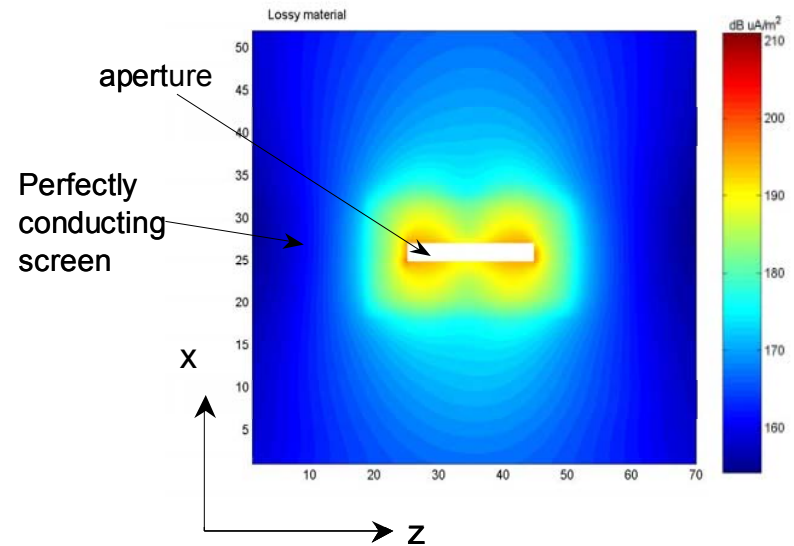




Surface Current Density Distribution



Before

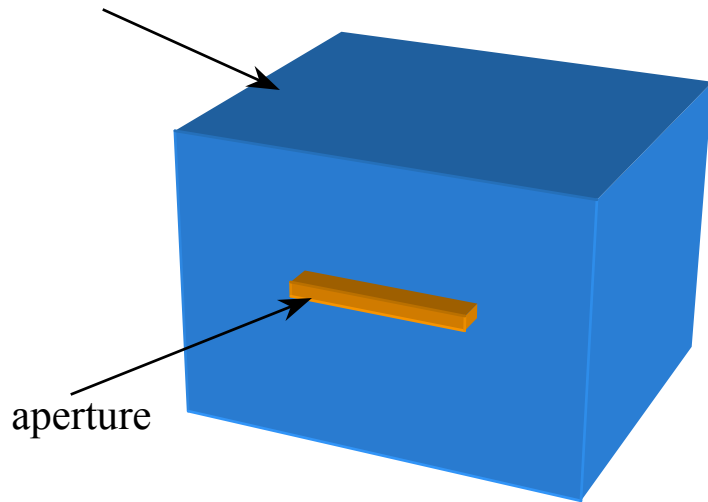


After

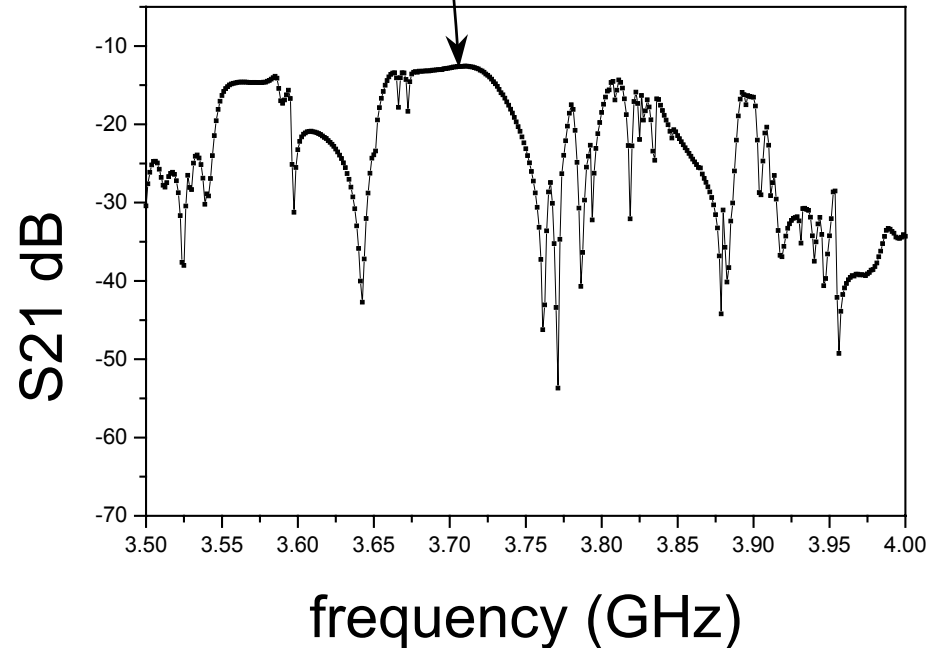


Effect of Coating on Aperture Field: Experimental Validation

Stainless steel
box



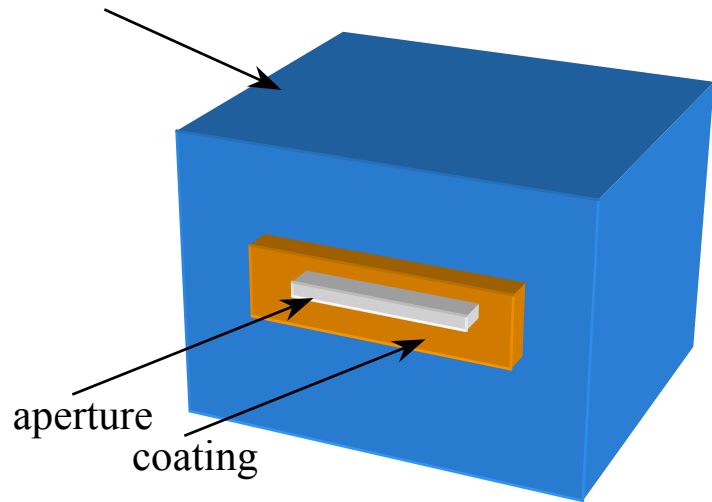
Without coating





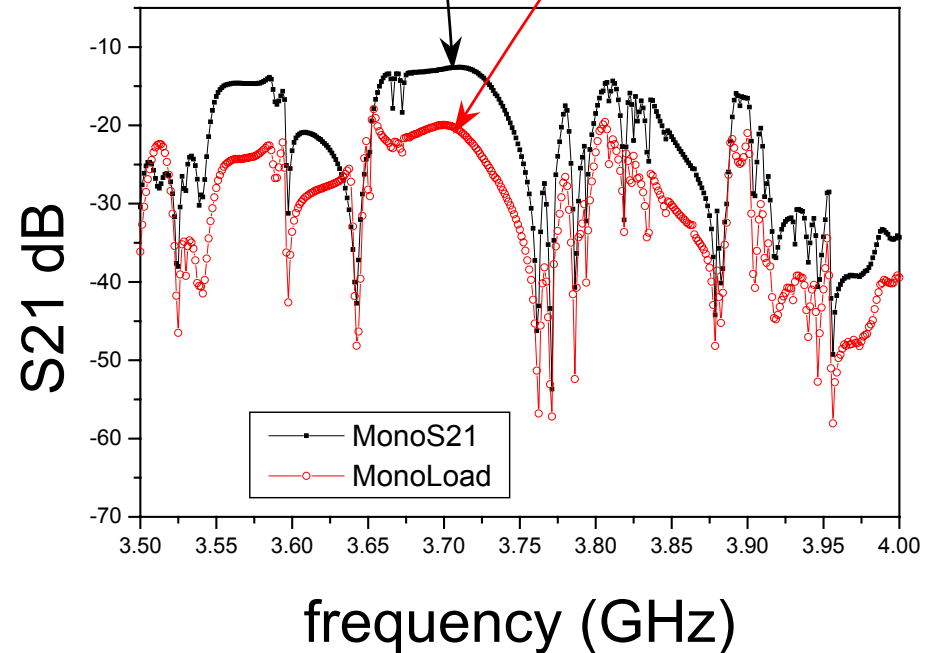
Effect of Coating on Aperture Field: Experimental Validation

Stainless steel
box



Without coating

With coating



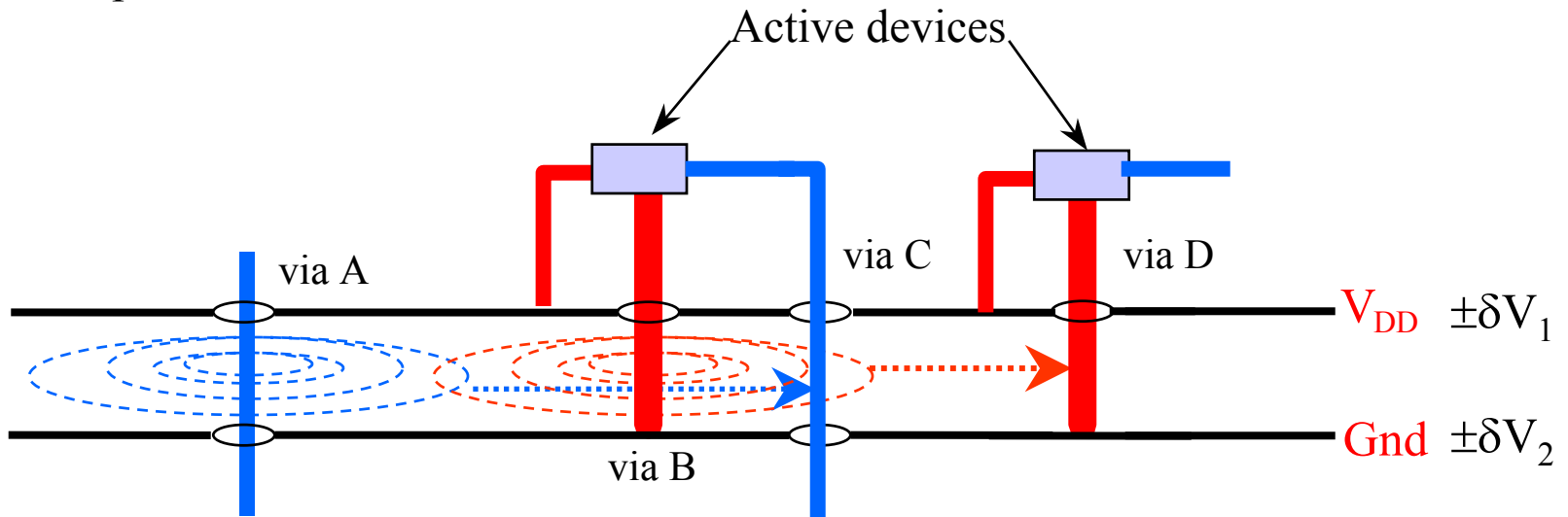


Part II: Reduce switching and other noise in Printed Circuit Boards



EM Noise in PCB

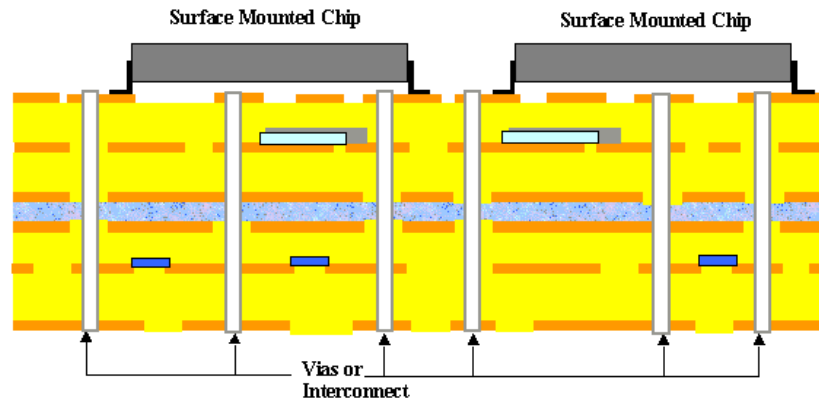
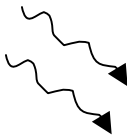
— signal
— power





Coupling to Sensitive Devices in a Multi-Layer Stack up

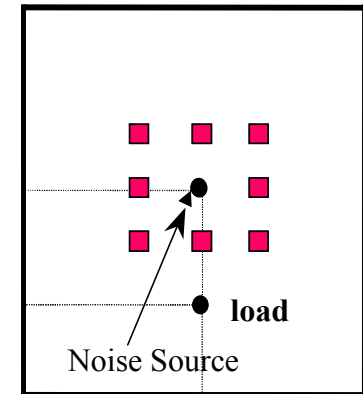
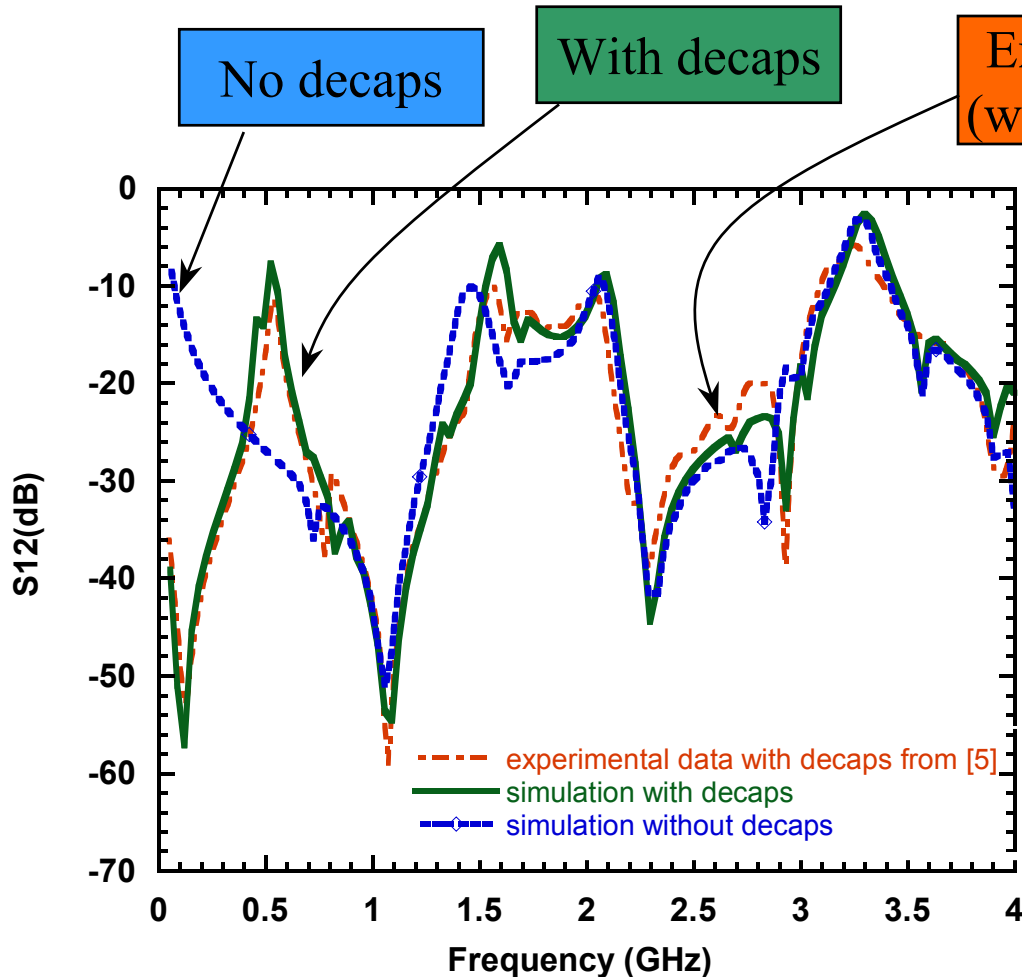
Incoming
radiation



outgoing
waves



Decoupling Capacitors around Noise Source

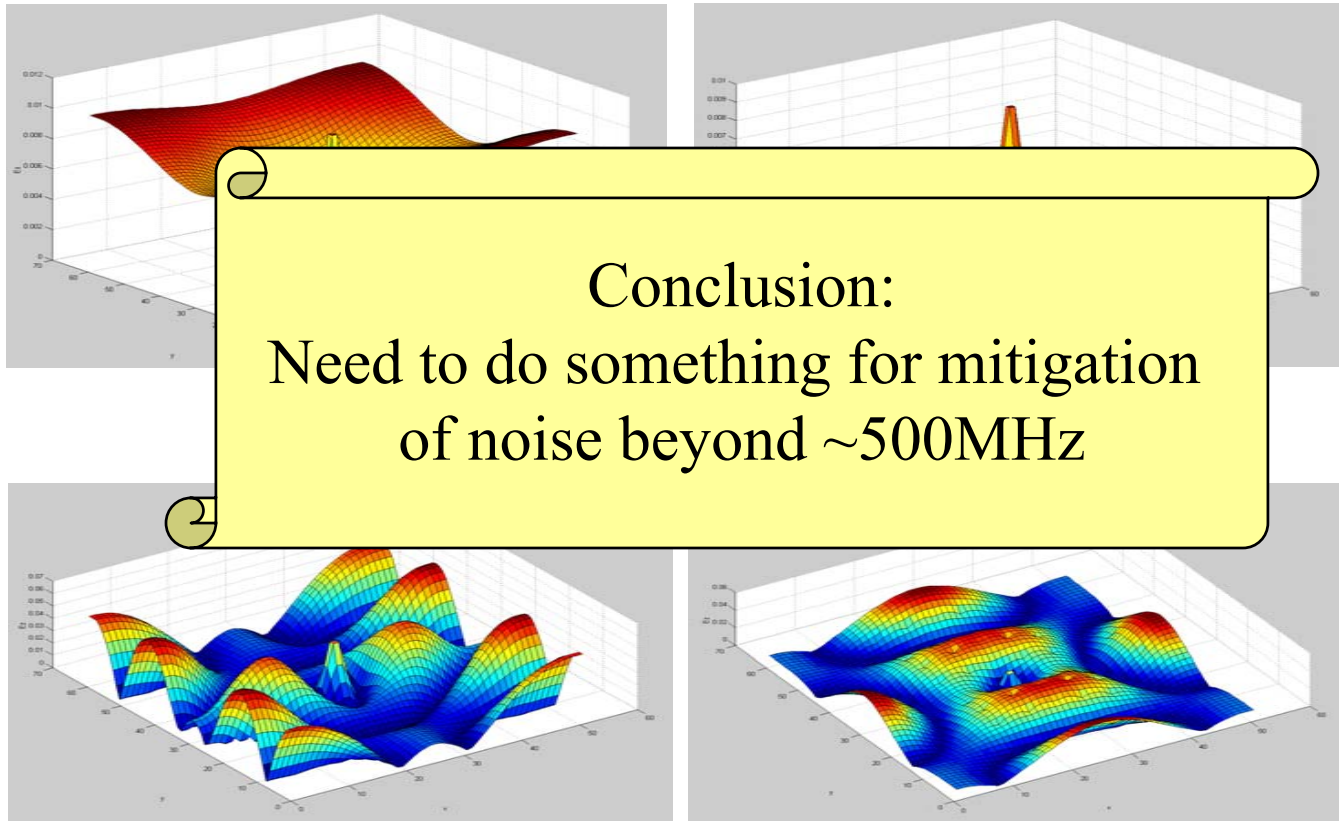


8 decoupling capacitors around noise source:
 $C=10\text{nF}$, $L=2\text{nH}$, $R=50\text{m}\Omega$



Classical Methods: Ineffective at Microwave Frequencies

- Effect of Capacitors Placement at 200MHz and 1GHz



no caps 1 GHz

99 caps 1 GHz

Conclusion:
Need to do something for mitigation
of noise beyond ~500MHz

Effective

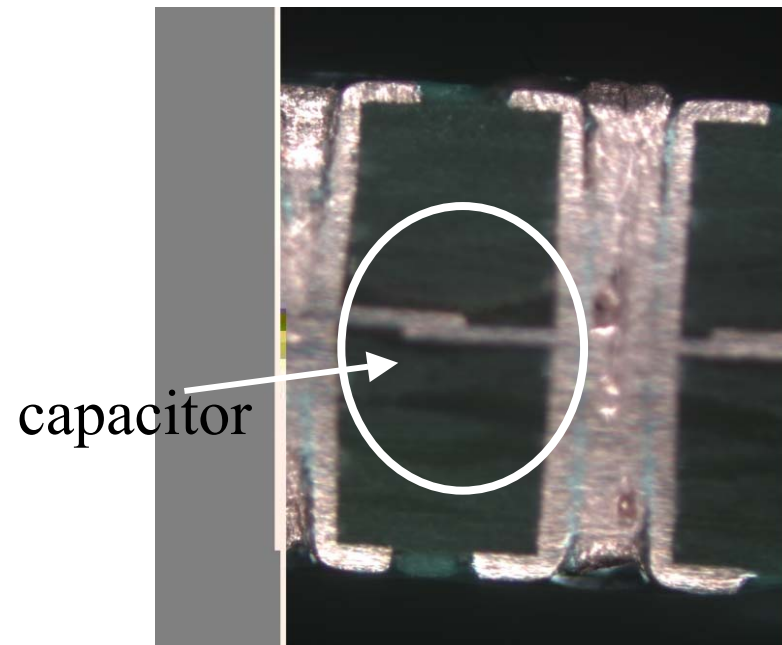
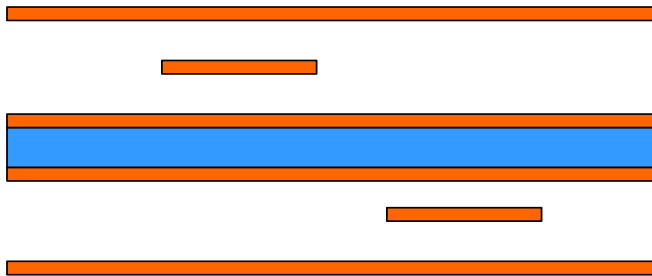
NOT
Effective



Possible Solutions

Embedded *Capacitors*

Embedded *Capacitance*



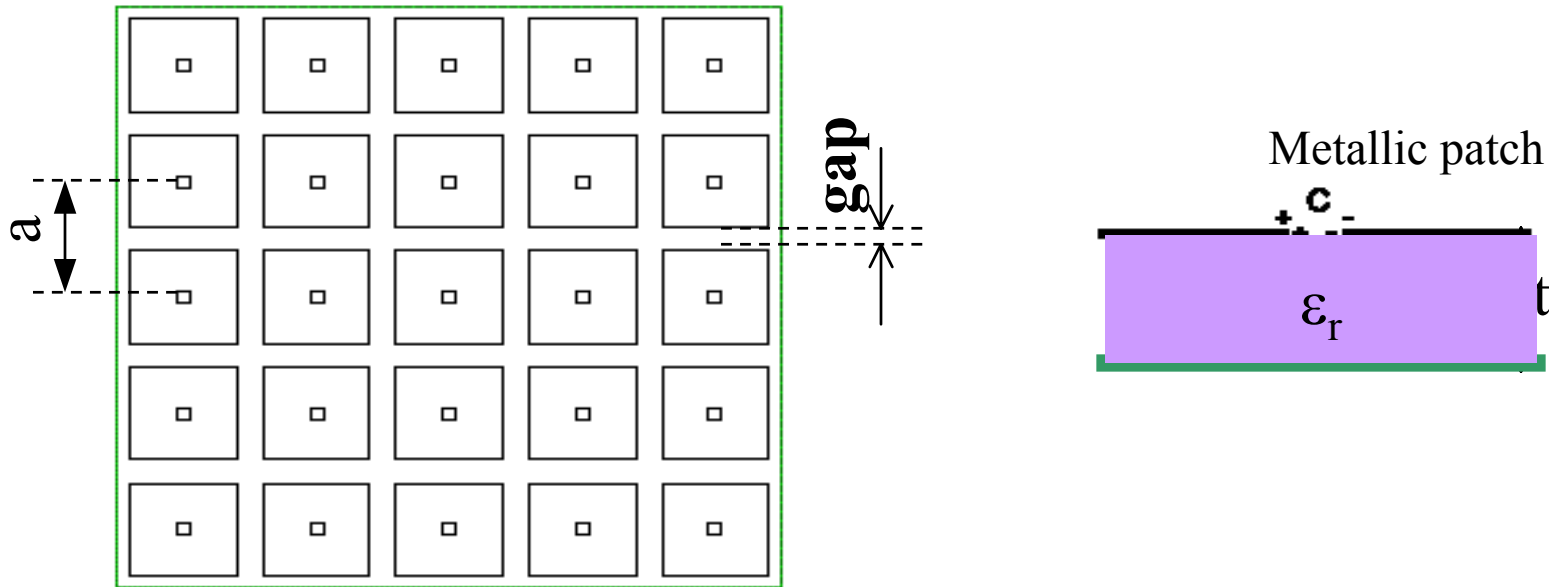


High-Impedance Surface

as a novel concept for switching
noise mitigation



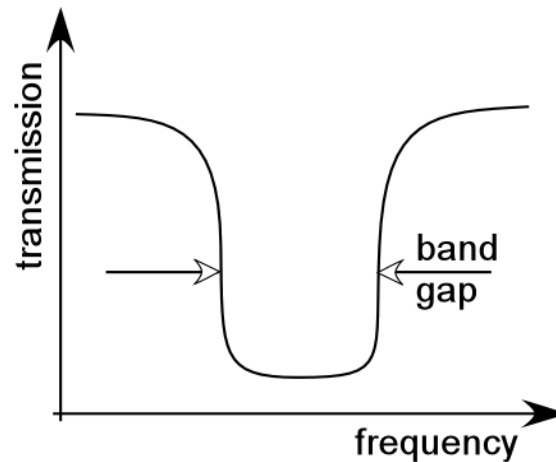
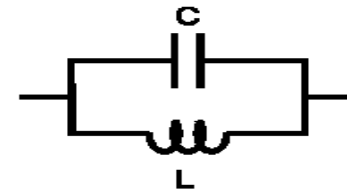
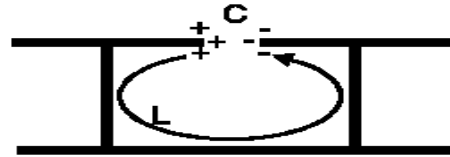
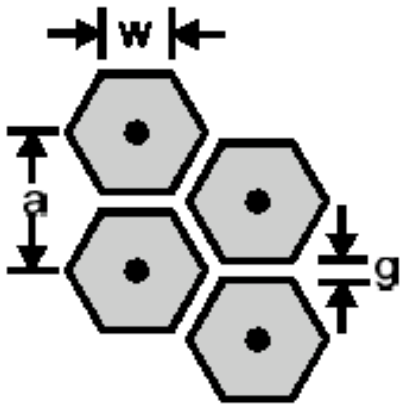
High-Impedance Surface for Surface Wave Suppression



Top view of HIS with square patches



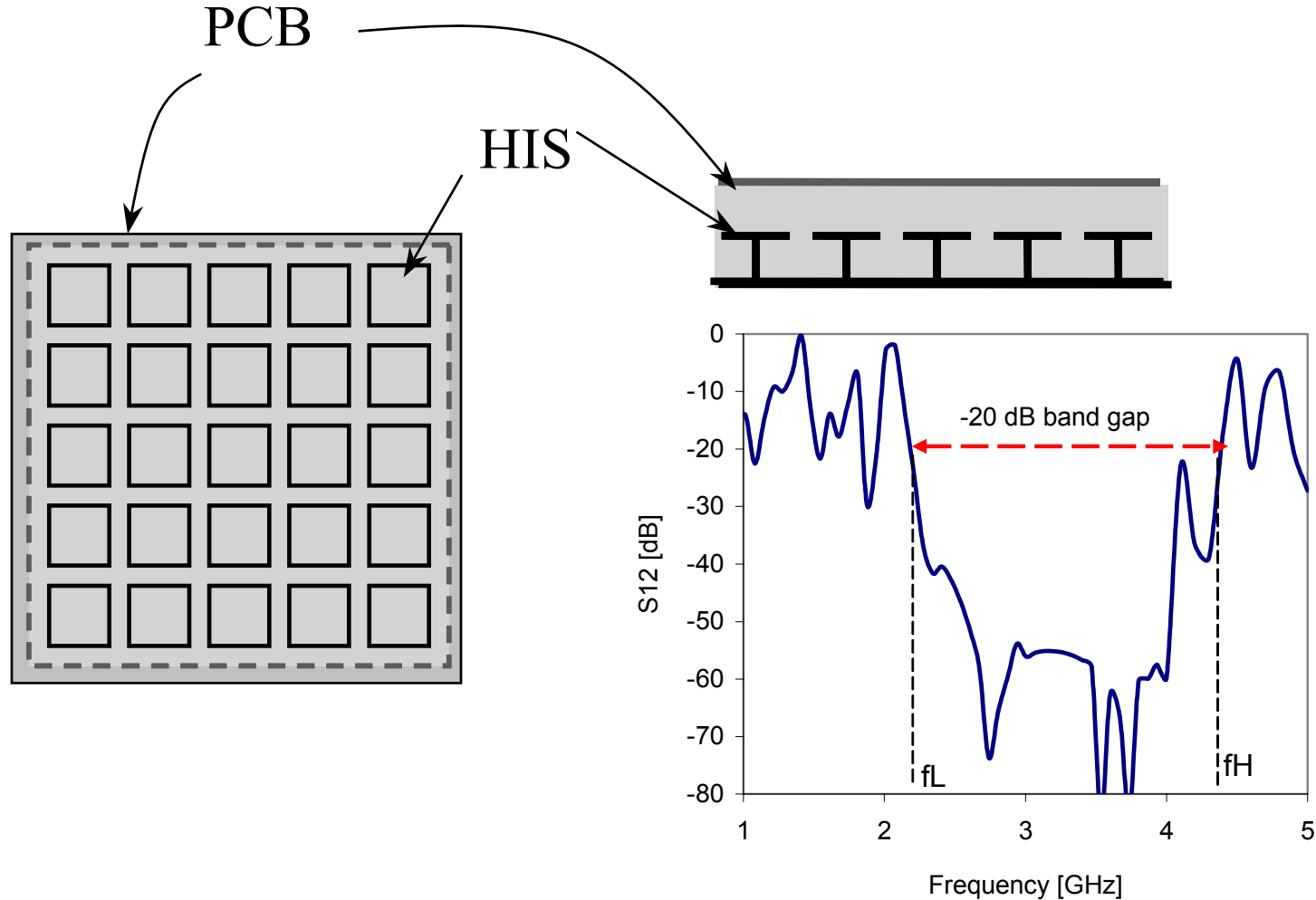
Interpretation: HIS as a Series of Parallel LC Resonators



$$\omega_0 = \frac{1}{\sqrt{LC}}$$

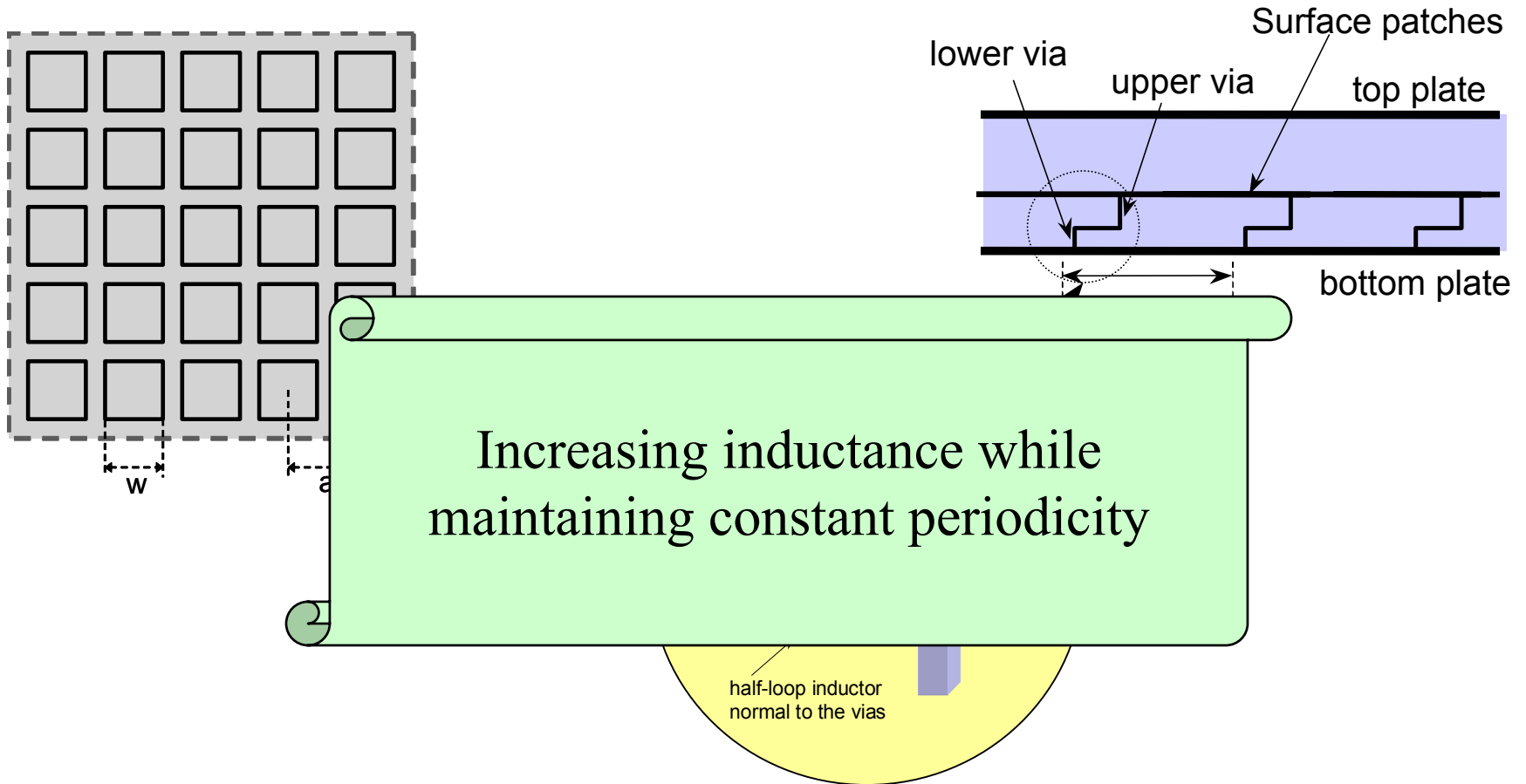


Power Plane with Embedded HIS





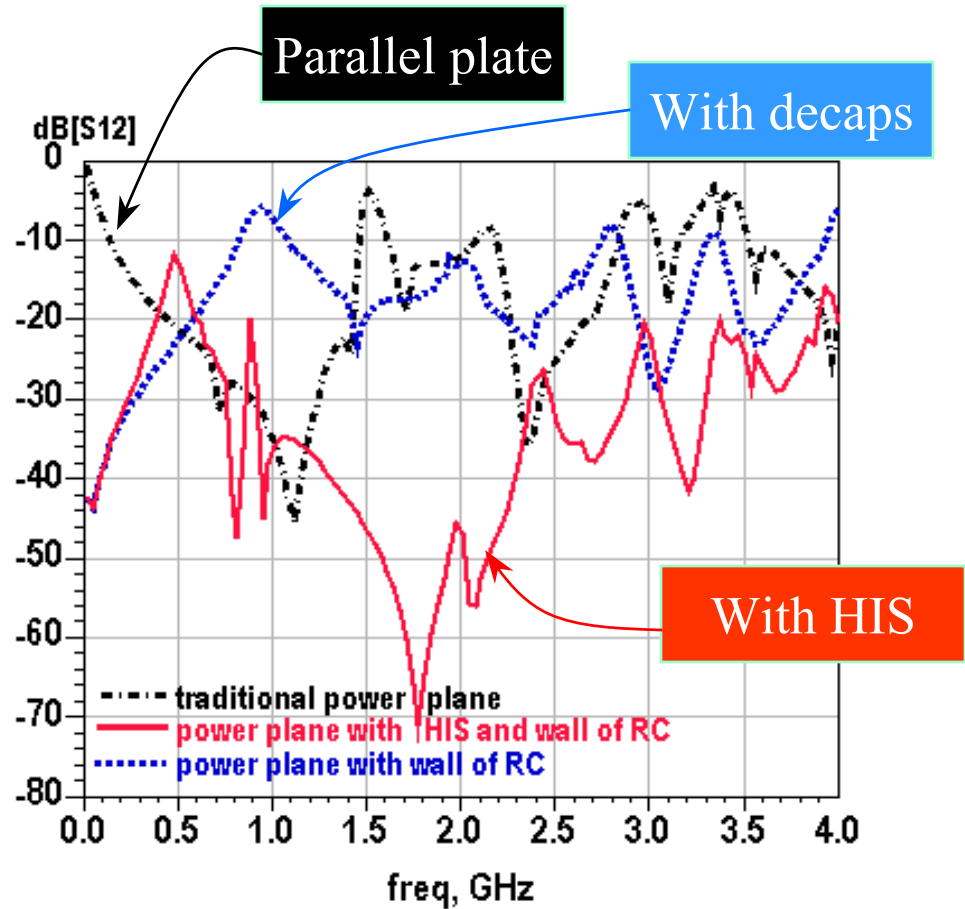
Widening the Gap!





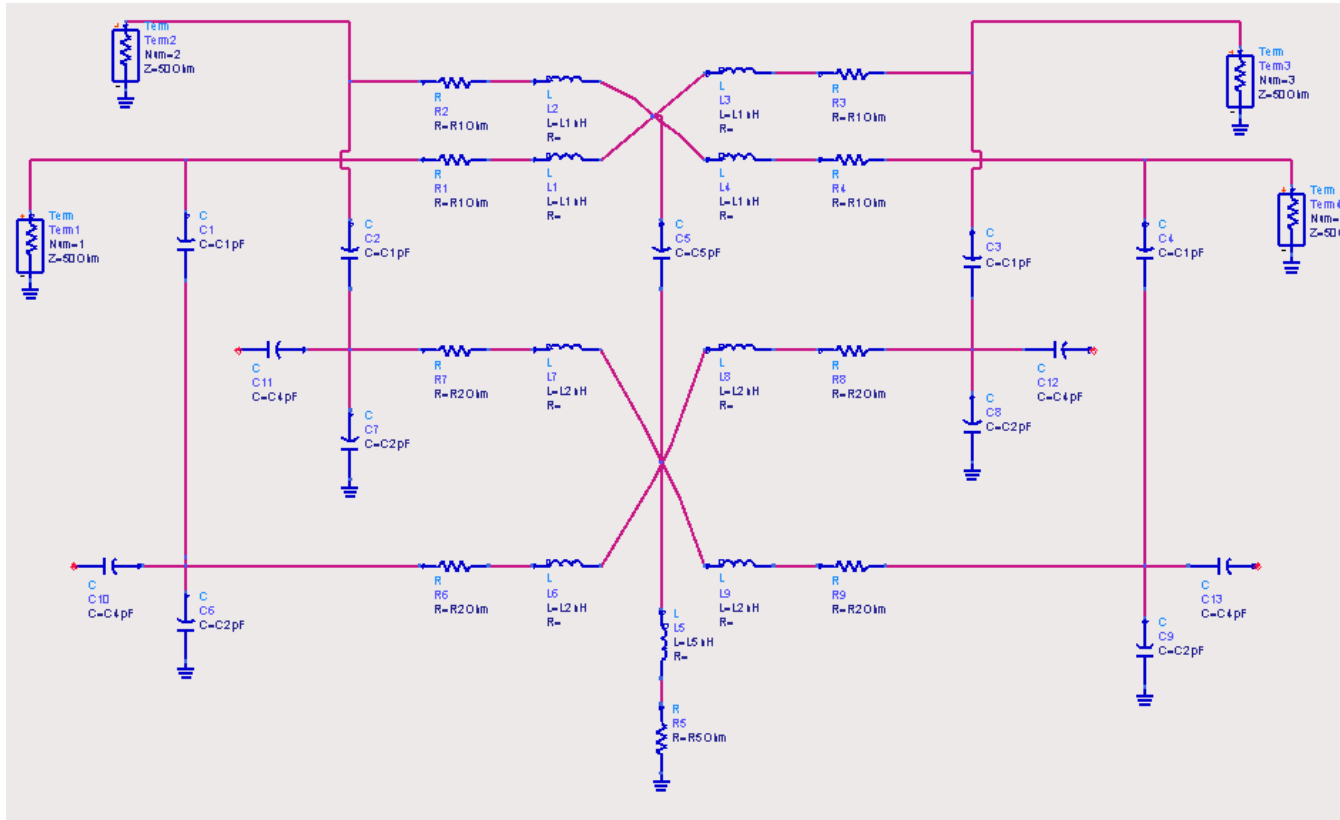
HIS Inductance-Enhanced Power Planes

Achieved a 3.2 GHz
-20 dB bandwidth!





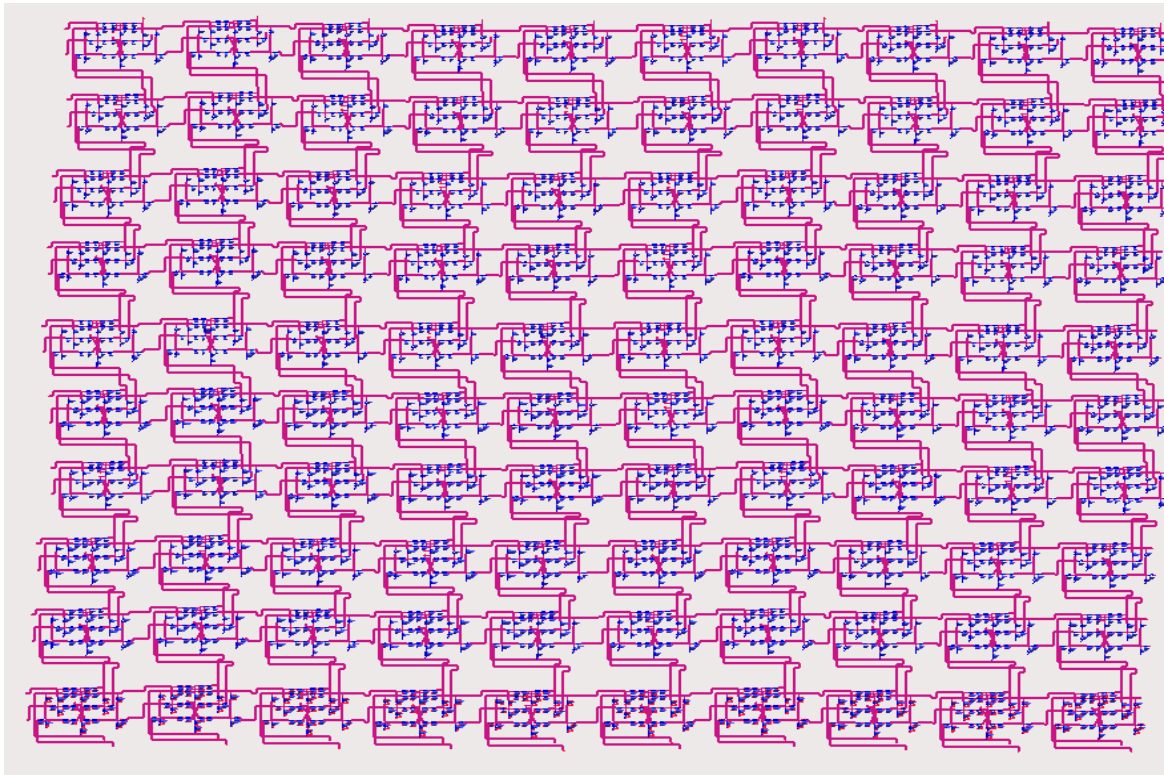
Physics-Based Model of a Unit Cell



} Top plate
} Substrate
} Patch
} Substrate



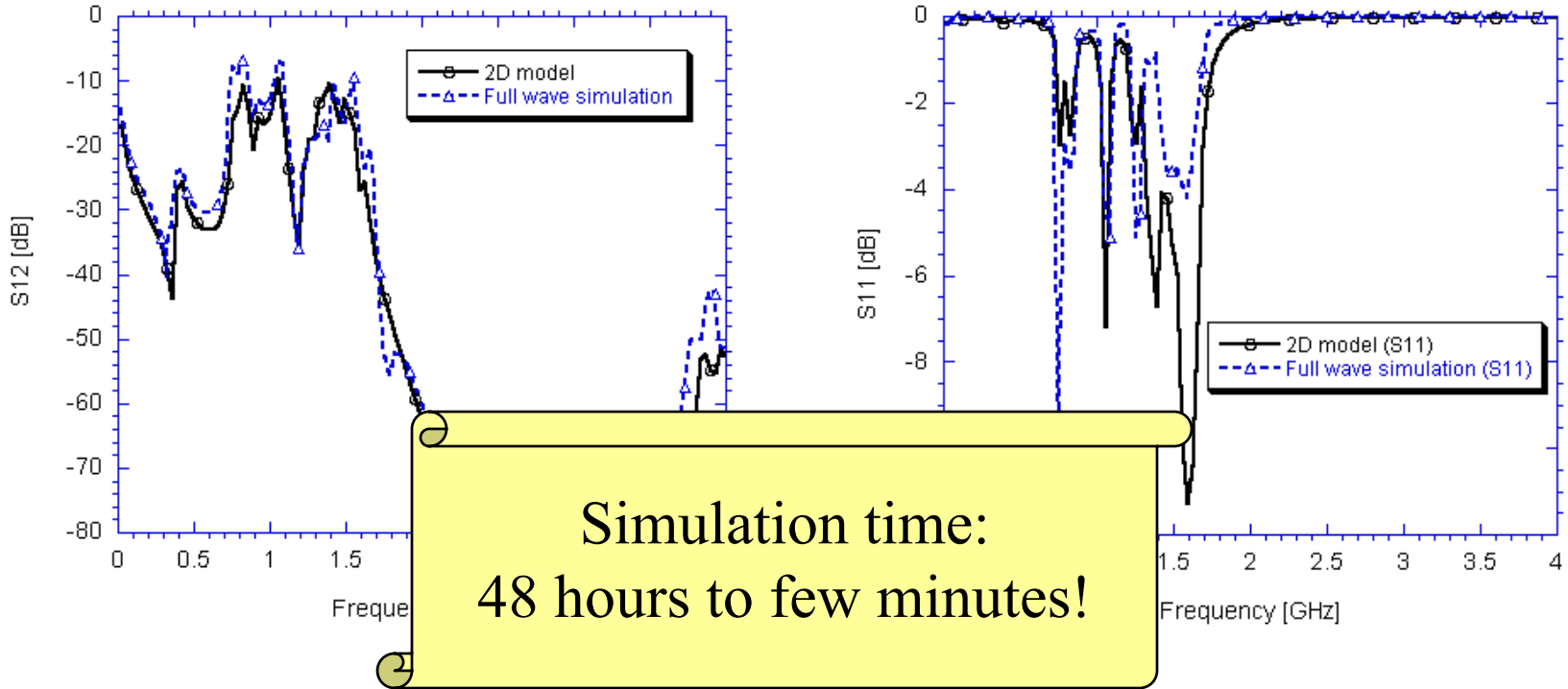
Compact Model of Complete Power Plane



2D cascaded model of a 10cmx10cm power
plane with a total of 100 cells



Full-Wave Model vs. Circuit Model

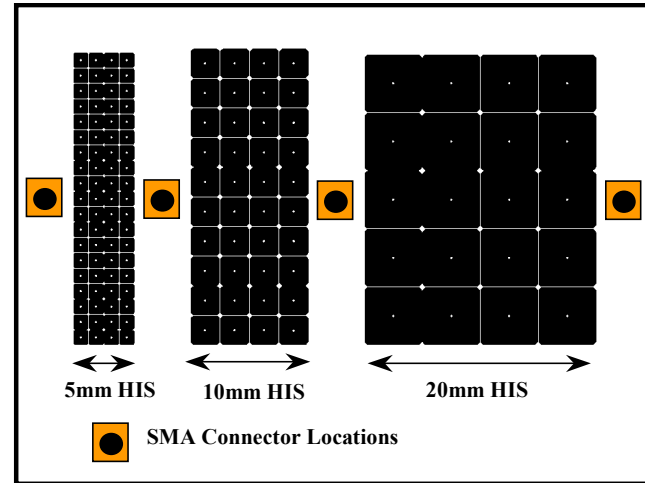




Wideband Noise Mitigation in PCBs

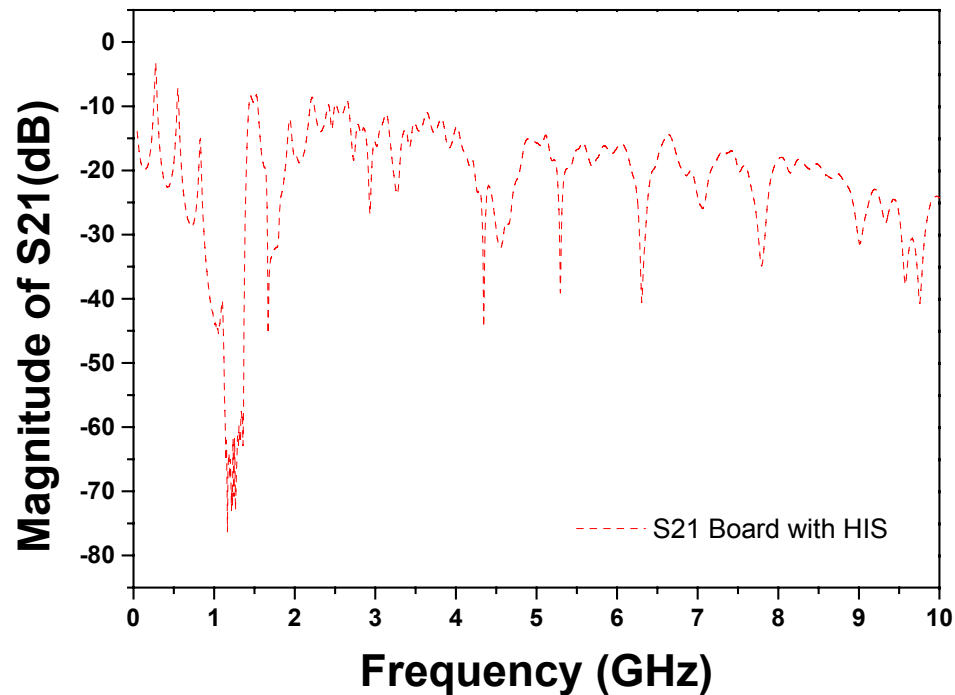
Can we increase the stop band?

Concept: cascaded filter design



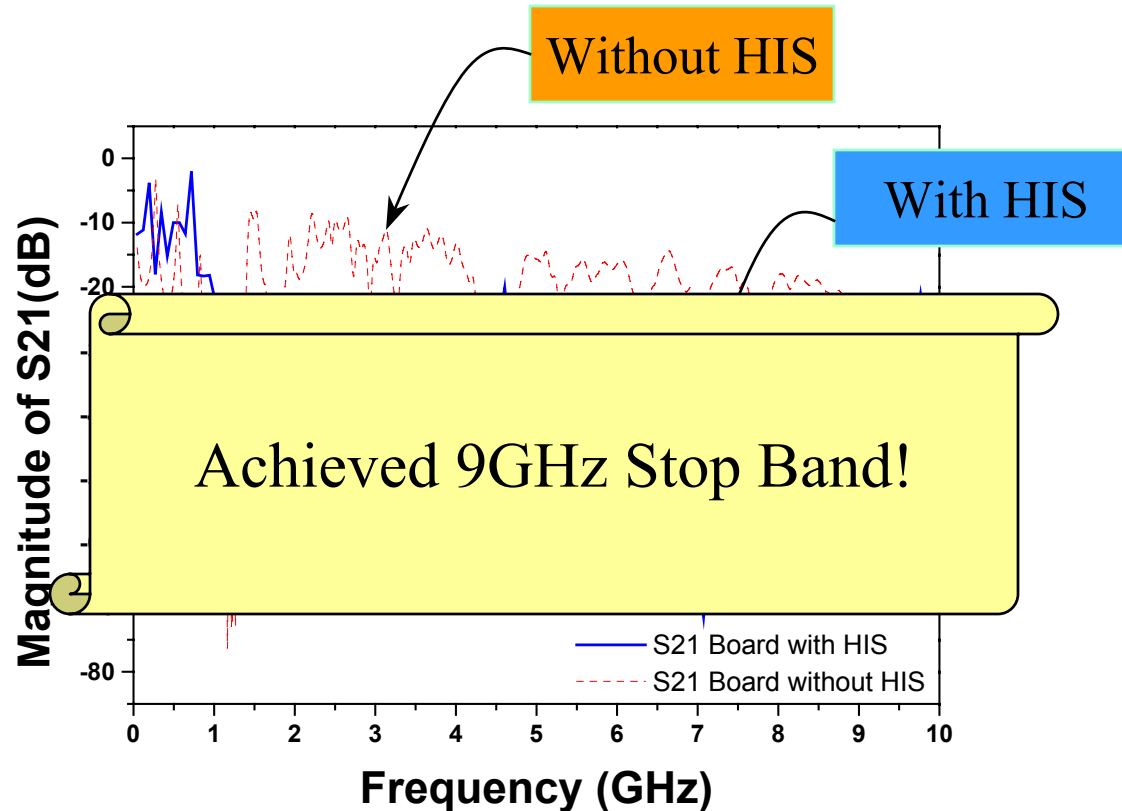


Experimental Validation





Experimental Validation



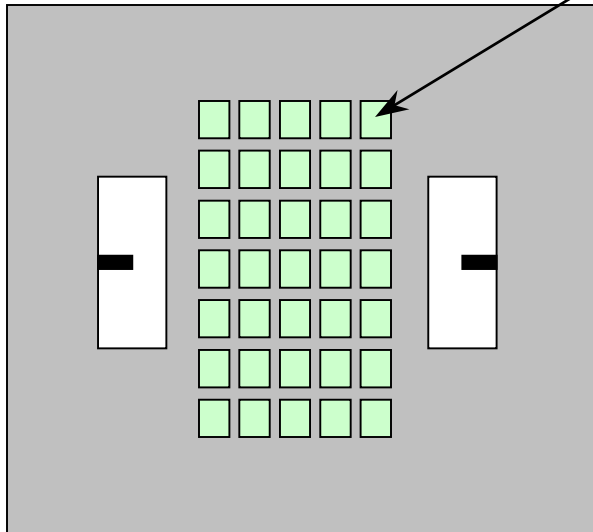


Part III: Reduction of coupling between cavities

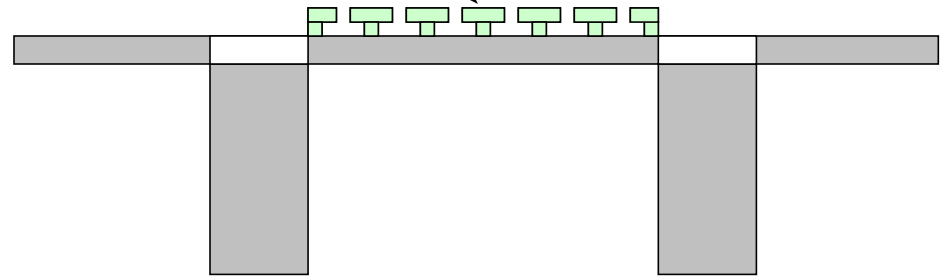


Close Proximity Cavities

HIS



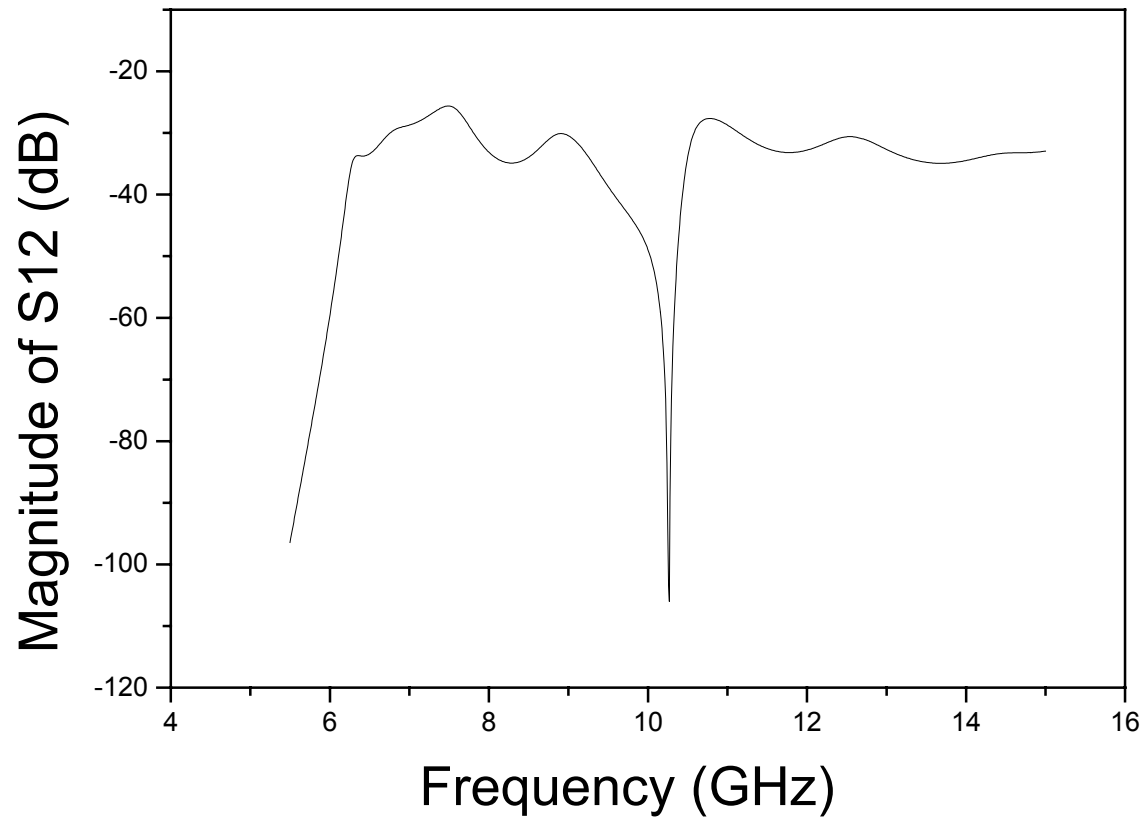
Top View



Side View

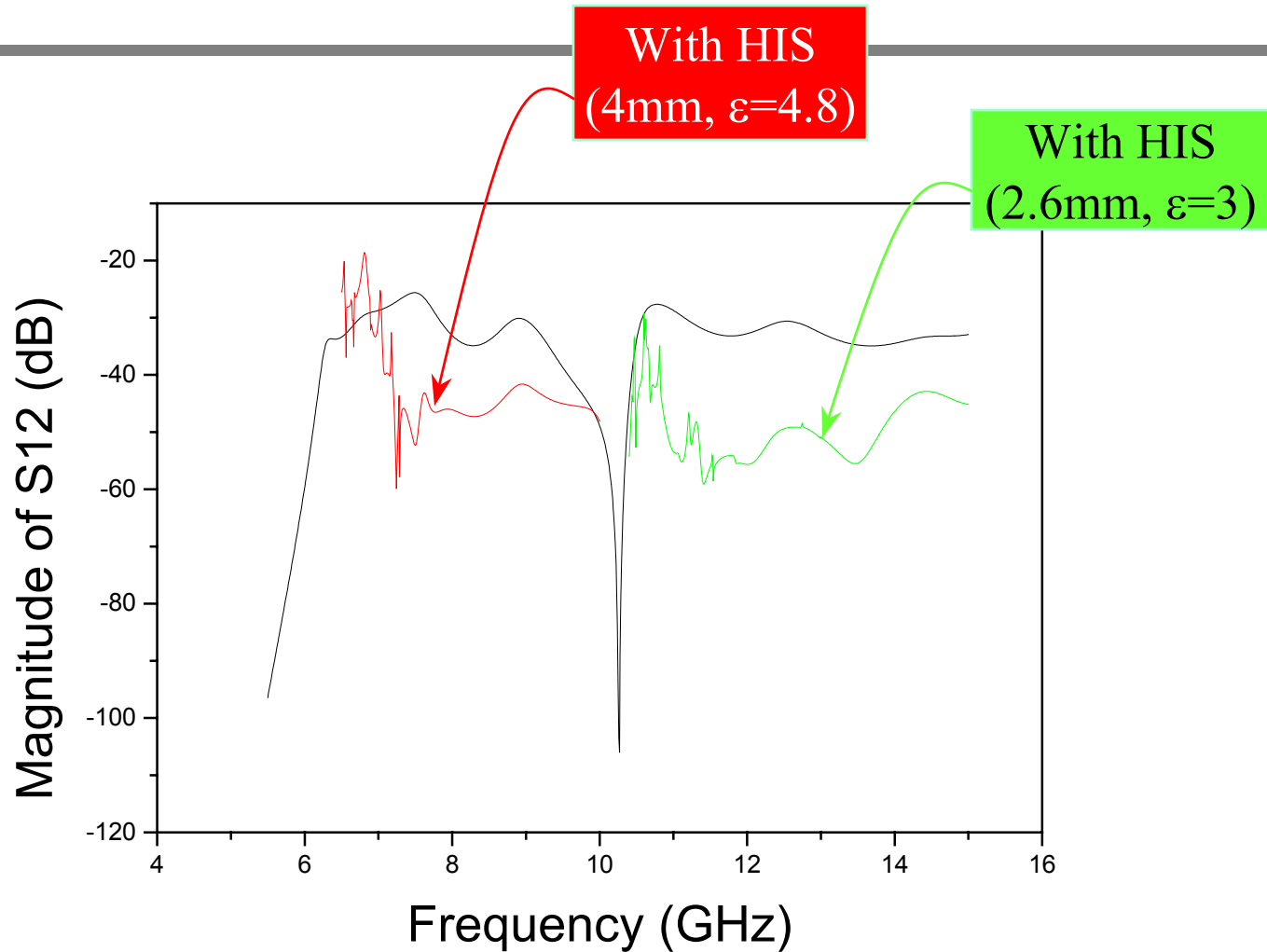


Effect of HIS on Coupling



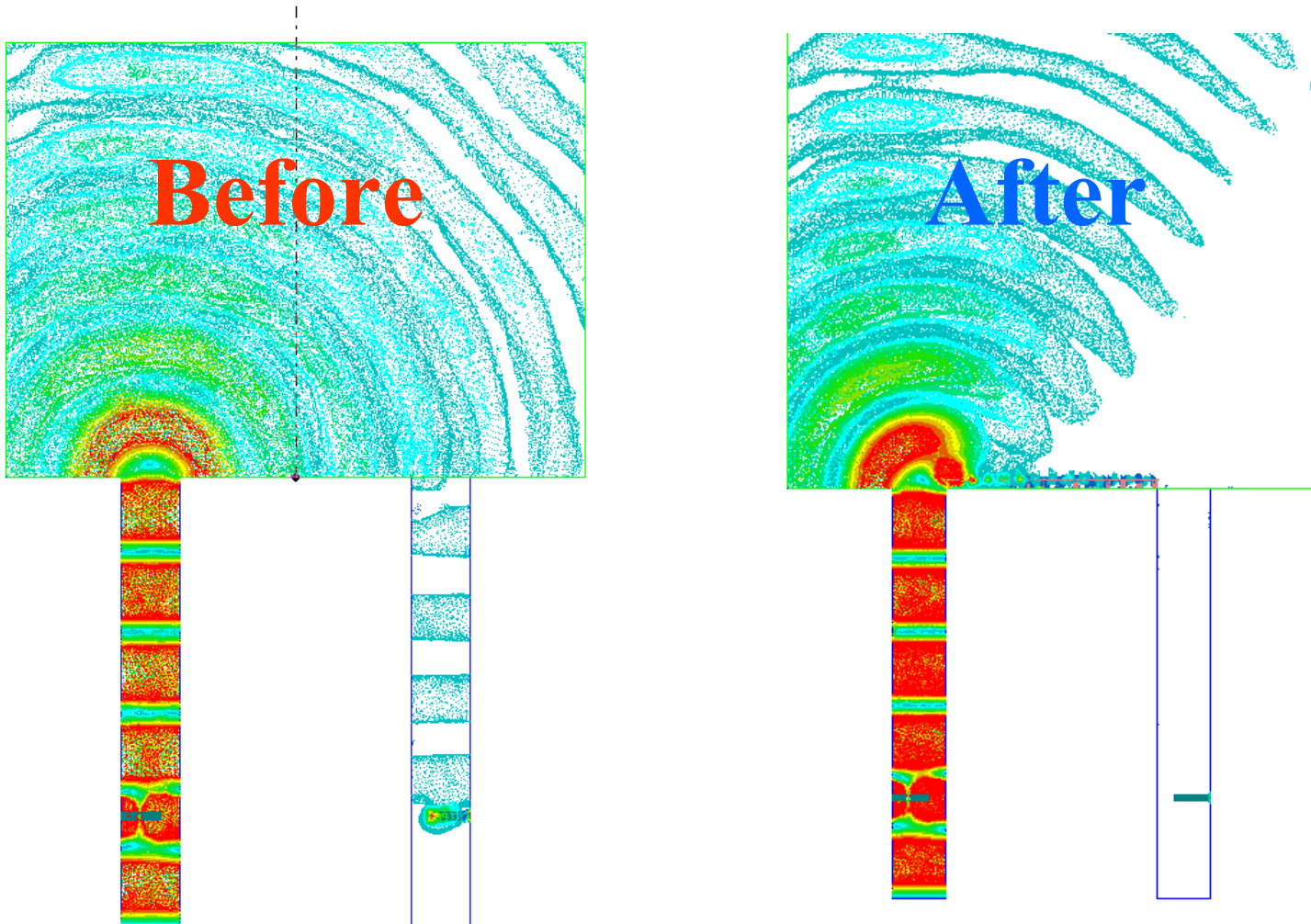


Effect of HIS on Coupling



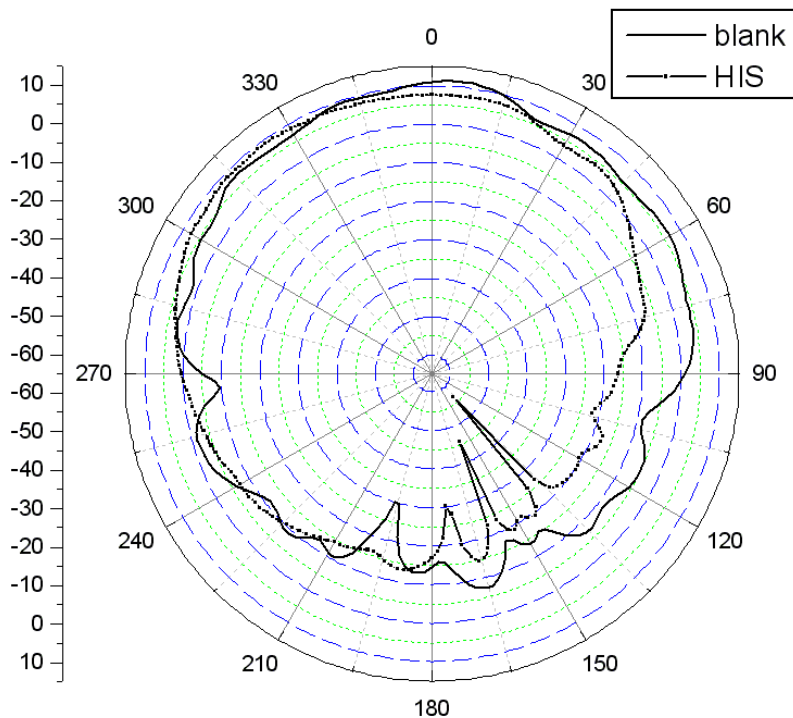


Field Pattern at 12.6GHz

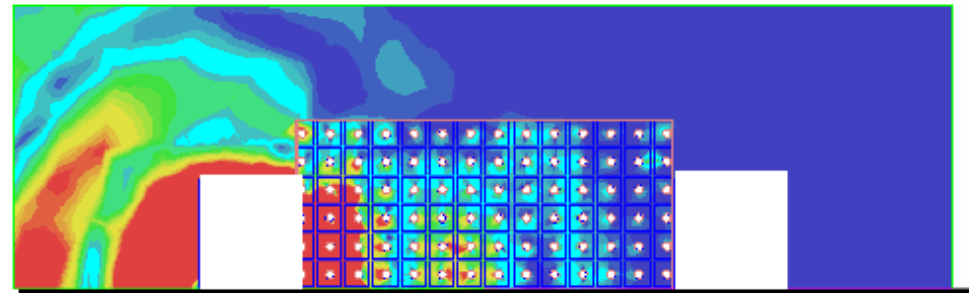




Field Patterns at 12.6GHz (H-plane)



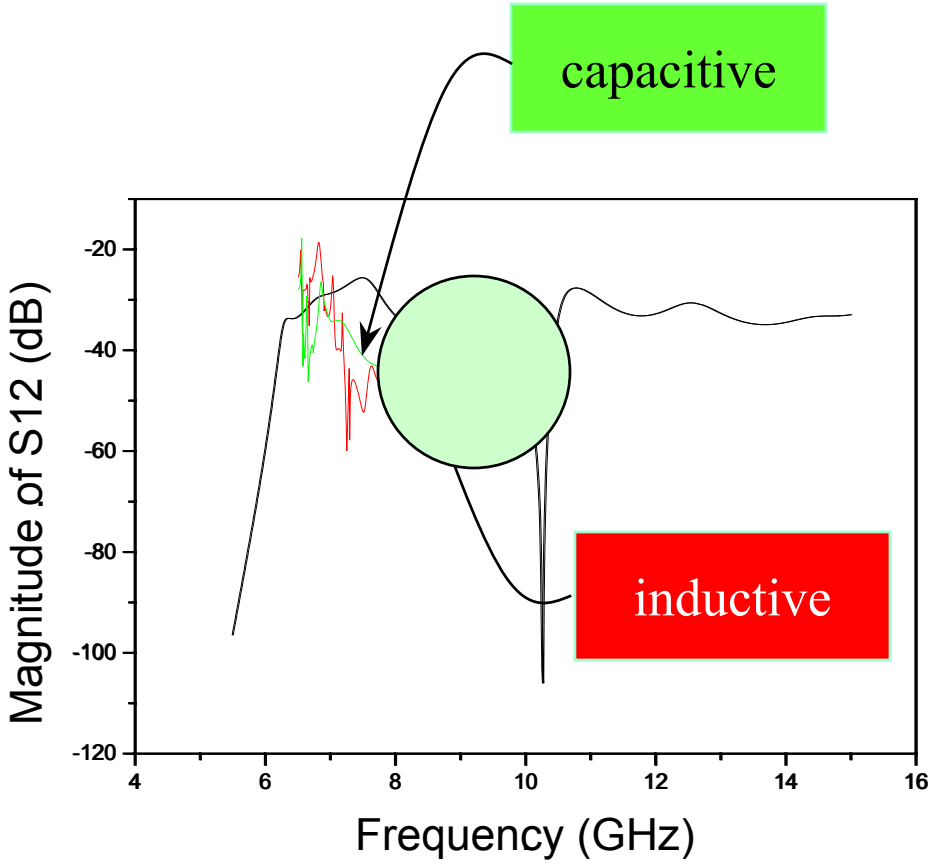
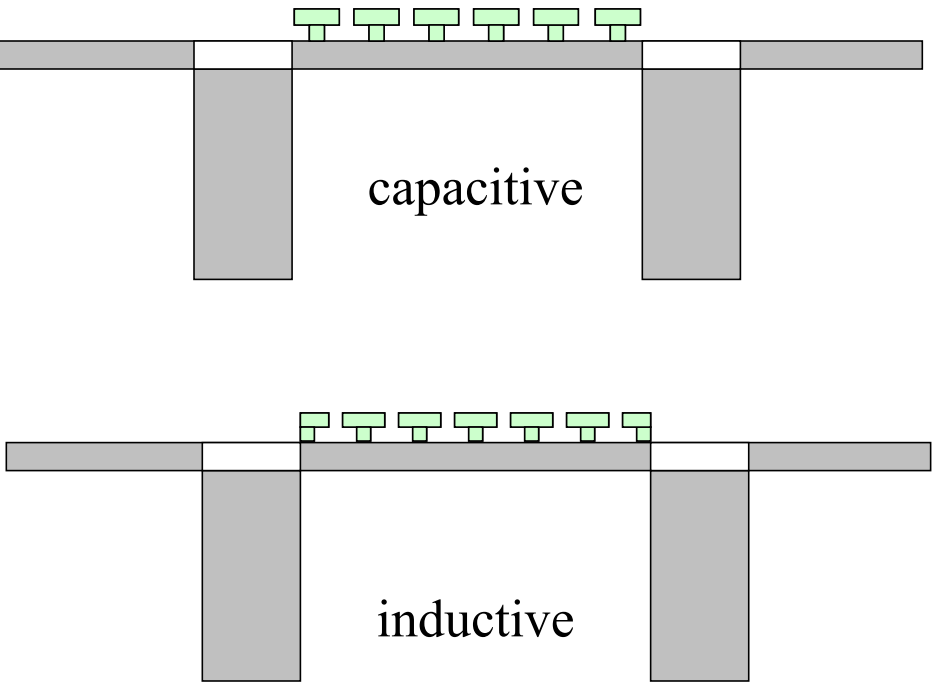
Radiation pattern



Top view



“Inductive” vs. “Capacitive” HIS

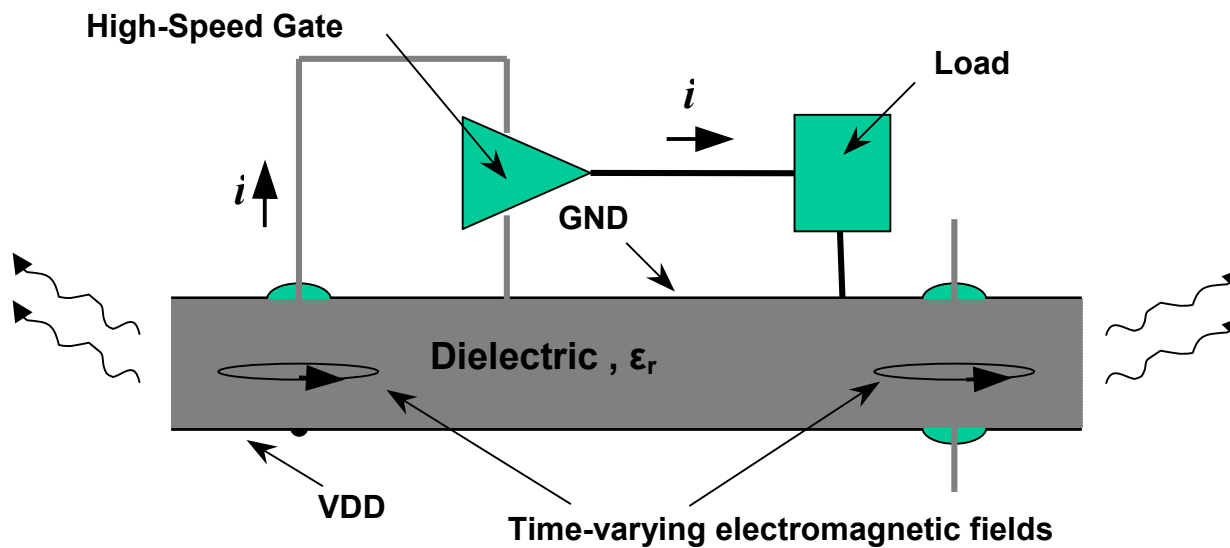




Part IV:
EMI Reduction from PCBs
(Interference and Immunity)



External Radiation from PCBs



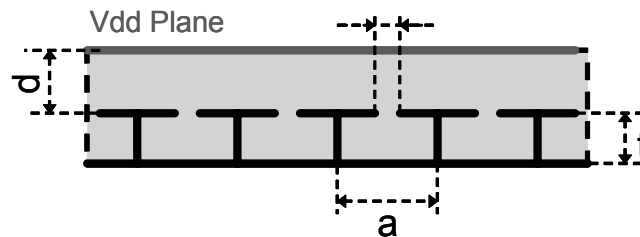


EMI Reduction through HIS

Concept:

Same as switching noise mitigation...

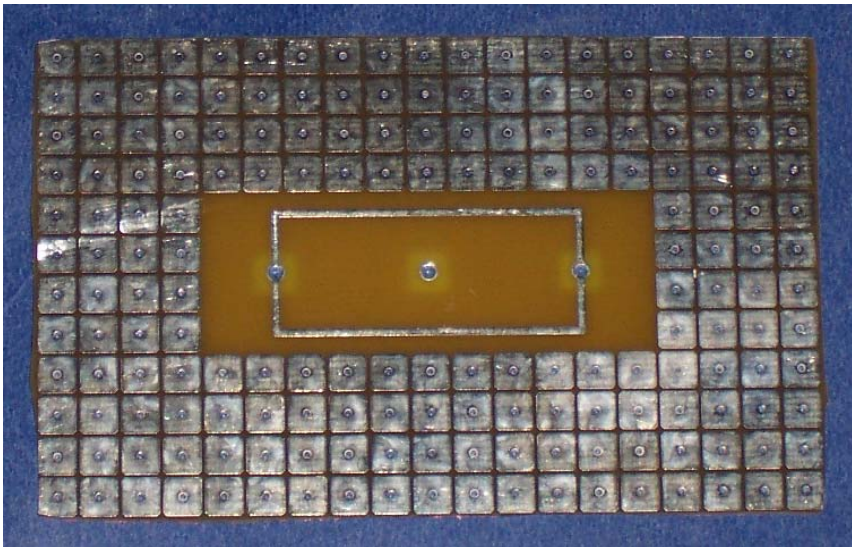
If waves don't travel within the PCB, they will not radiate!



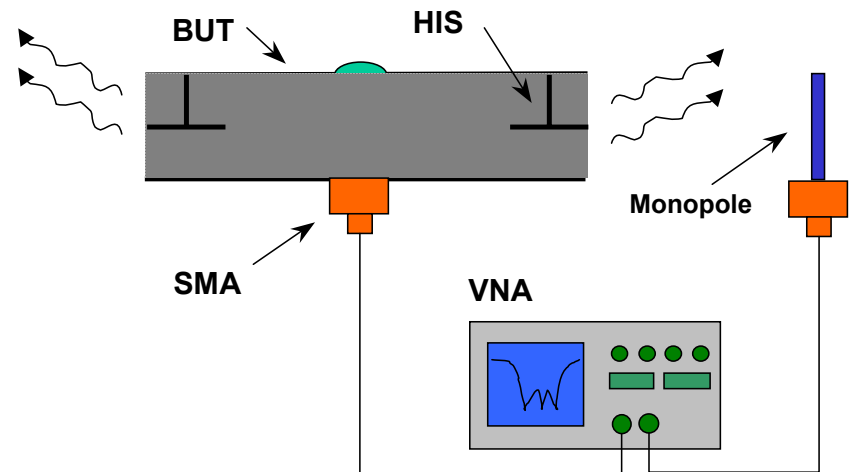


EMI Measurement Setup

5mm x 5mm patches

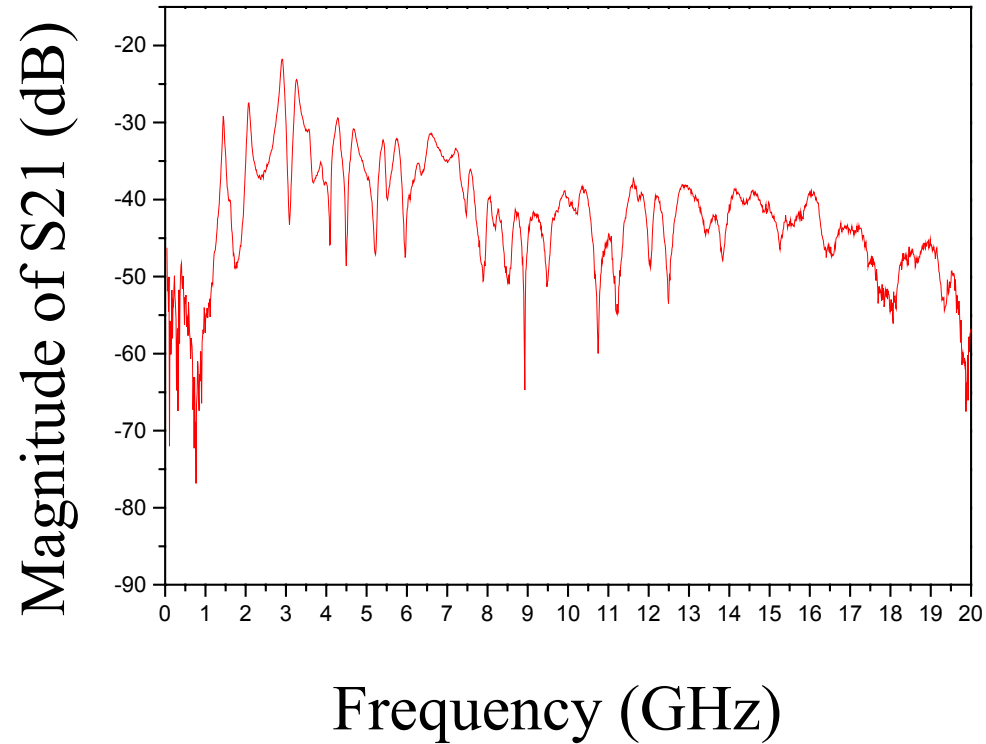


10cm x 6.5cm board



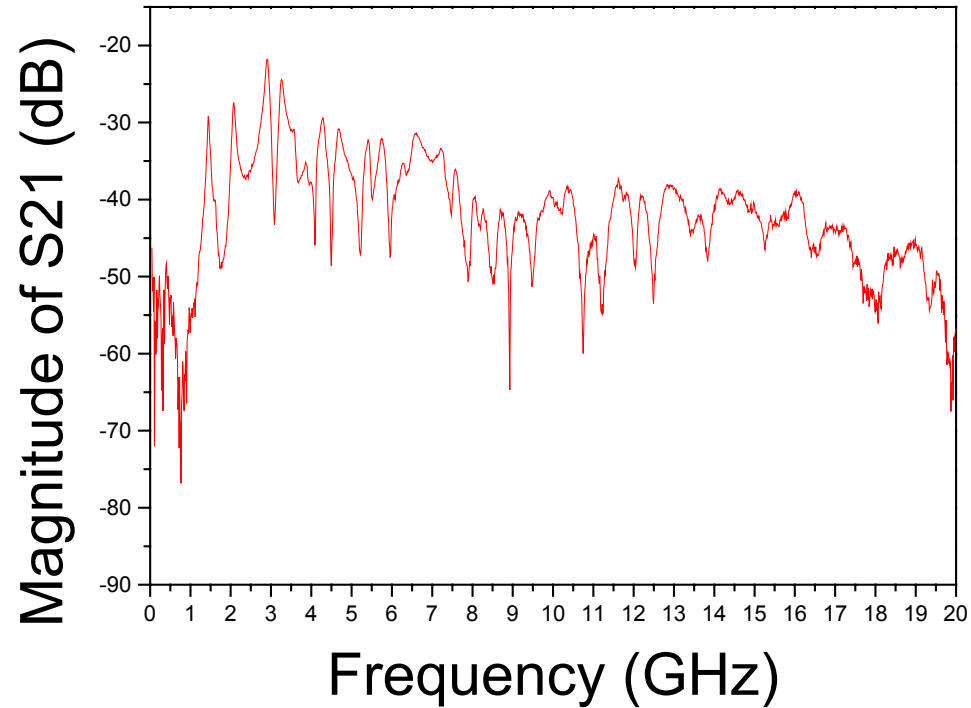


Effect of HIS on EMI



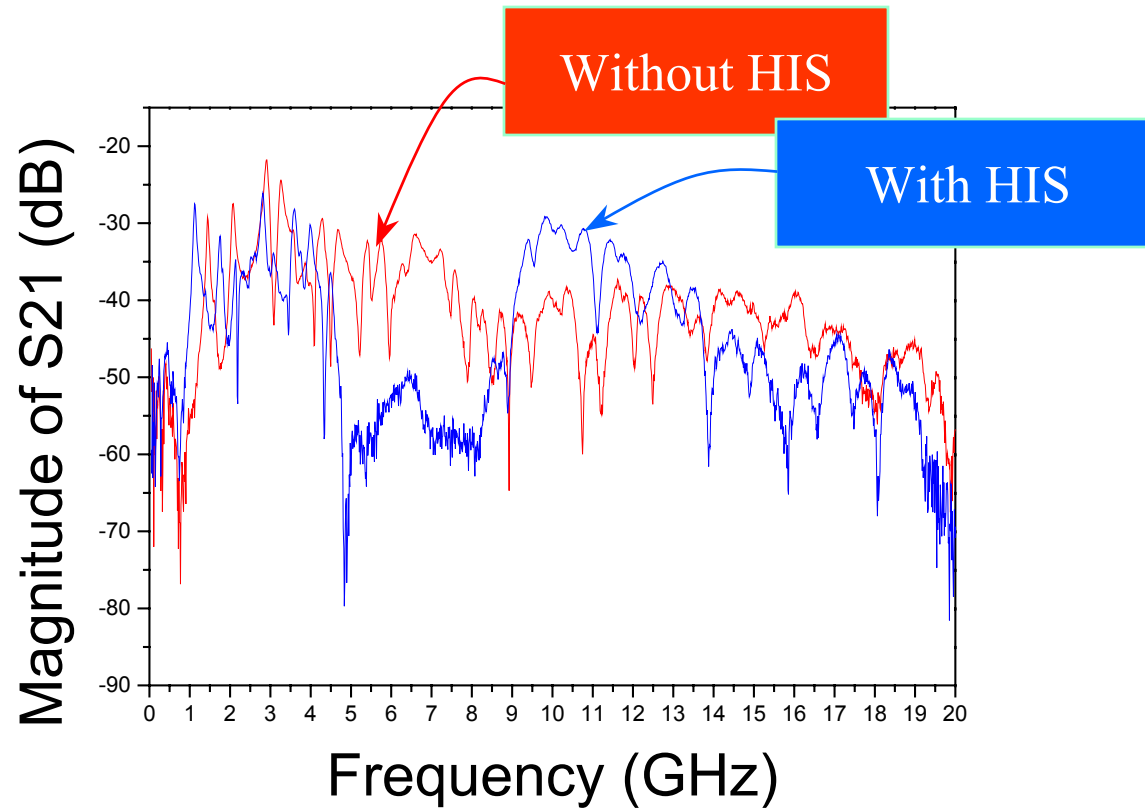


Effect of HIS on EMI





Effect of HIS on EMI





Present and Future Work

- Cavity radiation reduction using HIS
- Derivation of analytical expressions for some chaos cavities
- Reduced-size bandgap material for miniaturized systems
- Extension of the cascaded HIS concepts to general surface suppression applications



Present and Future Work

- Cavity radiation reduction using HIS
- Derivation of analytical expressions for some chaos cavities
- Reduced-size bandgap material for miniaturized systems
- Extension of the cascaded HIS concepts to general surface suppression applications



Present and Future Work

- Cavity radiation reduction using HIS
- Derivation of analytical expressions for some chaos cavities
- **Reduced-size bandgap material for miniaturized systems**
- Extension of the cascaded HIS concepts to general surface suppression applications



Present and Future Work

- Cavity radiation reduction using HIS
- Derivation of analytical expressions for some chaos cavities
- Reduced-size bandgap material for miniaturized systems
- Extension of the cascaded HIS concepts to general surface suppression applications